

AMENDMENTS TO THE ABSTRACT

Please amend the abstract as follows:

The present embodiments and associated methods provide for an integrated EMI shield for effective shielding not only from emissions perpendicular to the integrated circuit (IC) chip carrier but also parallel (edgewise) to the carrier. In one embodiment, ~~an IC chip carrier comprises an insulating ceramic substrate and at least one internal electrically conductive layer being a circuit ground, portions of which extend to the edge of the substrate, the internal electrically conductive layer in electrical contact with an electrically conductive layer applied to a portion of the substrate edge. This provides a horizontal hybrid ground plane which can be used as an EMI shield that runs horizontally to the chip as well as a hybrid edge EMI shield perpendicular along at least a portion of the edge. This edge shield protects internal circuitry from exterior EMI emissions directed towards the chip carrier edge portion incorporating the shield~~ a method includes forming at least a portion of an internal ground layer along at least a portion of a chip carrier edge, applying an electrically conductive layer to at least a portion of the chip carrier edge, the conductive layer being applied over the exposed portion of the ground layer and in electrical contact with said ground layer, and forming at least one cavity within the top surface of the chip carrier, where the at least one cavity configured to hold one or more integrated circuit chips therein.